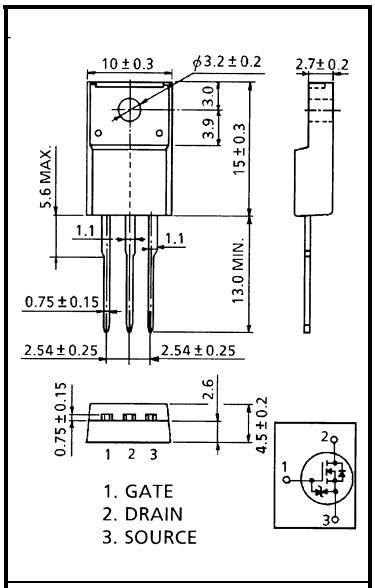
TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π−MOSIII)

2SK2718

DC−DC Converter and Motor Drive Applications

- Low drain−source ON resistance : $R_{DS\ (ON)}$ = 5.6 Ω (typ.)
- High forward transfer admittance : $|Y_{fs}|$ = 2.0 S (typ.)
- Low leakage current : I_{DSS} = 100 μA (max) (V_{DS} = 720 V)
- Enhancement mode : V_{th} = 2.0~4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Unit: mm



JEDEC	—
JEITA	SC-67
TOSHIBA	2-10R1B

Weight: 1.9 g (typ.)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain−source voltage		V_{DSS}	900	V
Drain−gate voltage (R_{GS} = 20 kΩ)		V_{DGR}	900	V
Gate−source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	I_D	2.5	A
	Pulse (Note 1)	I_{DP}	7.5	A
Drain power dissipation (Tc = 25°C)		P_D	40	W
Single pulse avalanche energy (Note 2)		E_{AS}	216	mJ
Avalanche current		I_{AR}	2.5	A
Repetitive avalanche energy (Note 3)		E_{AR}	4.0	mJ
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	−55~150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th\ (ch-c)}$	3.125	°C / W
Thermal resistance, channel to ambient	$R_{th\ (ch-a)}$	62.5	°C / W

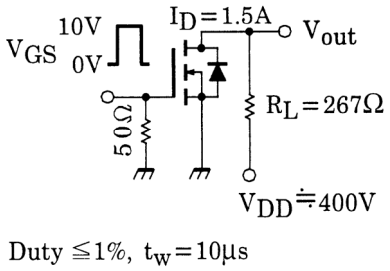
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 63.4 mH, R_G = 25 Ω, I_{AR} = 2.5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.
Please handle with caution.

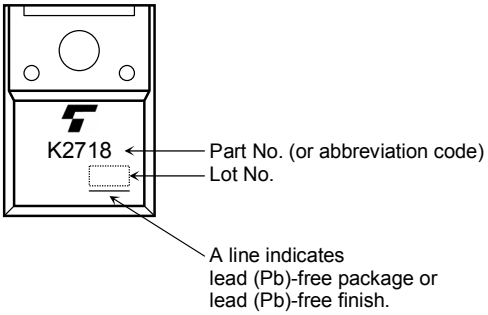
Electrical Characteristics (Ta = 25°C)

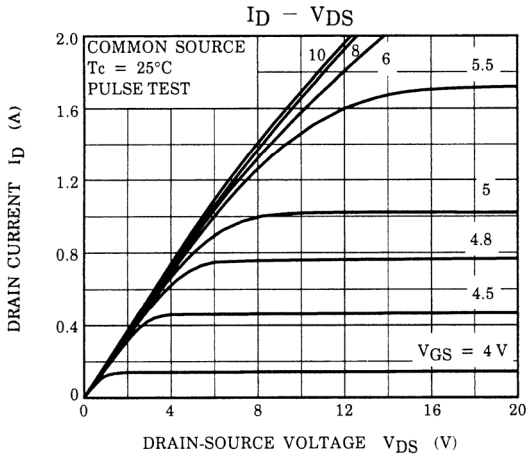
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	V_{GS} = ±25 V, V_{DS} = 0 V	—	—	±10	μA
Gate−source breakdown voltage		$V_{(BR)\ GSS}$	I_G = ±10 μA, V_{DS} = 0 V	±30	—	—	V
Drain cut−off current		I_{DSS}	V_{DS} = 720 V, V_{GS} = 0 V	—	—	100	μA
Drain−source breakdown voltage		$V_{(BR)\ DSS}$	I_D = 10 mA, V_{GS} = 0 V	900	—	—	V
Gate threshold voltage		V_{th}	V_{DS} = 10 V, I_D = 1 mA	2.0	—	4.0	V
Drain−source ON resistance		$R_{DS\ (ON)}$	V_{GS} = 10 V, I_D = 1.5 A	—	5.6	6.4	Ω
Forward transfer admittance		$\|Y_{fs}\|$	V_{DS} = 20 V, I_D = 1.5 A	1.0	2.0	—	S
Input capacitance		C_{iss}	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz	—	510	—	pF
Reverse transfer capacitance		C_{rss}		—	10	—	
Output capacitance		C_{oss}		—	55	—	
Switching time	Rise time	t_r		—	20	—	ns
	Turn−on time	t_{on}		—	60	—	
	Fall time	t_f		—	40	—	
	Turn−off time	t_{off}		—	115	—	
Total gate charge (gate−source plus gate−drain)		Q_g	V_{DD} ≈ 400 V, V_{GS} = 10 V, I_D = 2.5 A	—	21	—	nC
Gate−source charge		Q_{gs}		—	11	—	
Gate−drain ("miller") Charge		Q_{gd}		—	10	—	

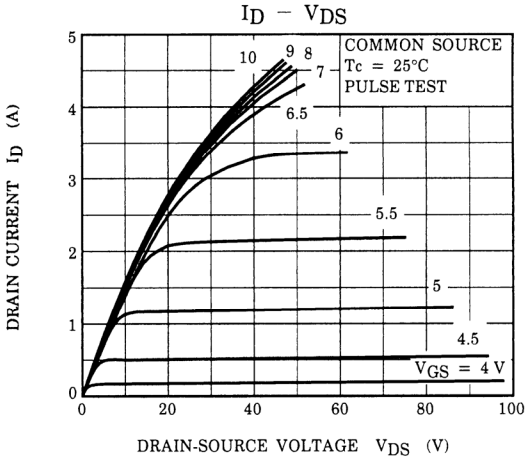
Source−Drain Ratings and Characteristics (Ta = 25°C)

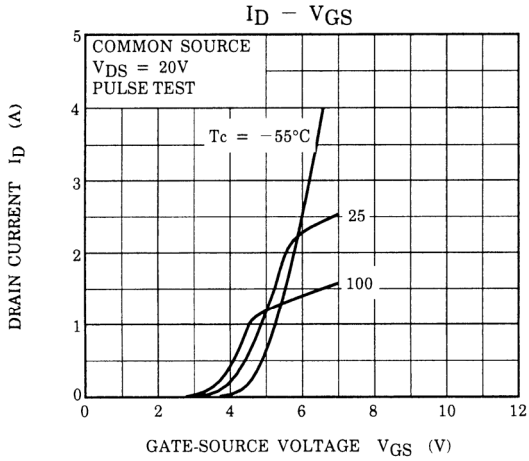
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	2.5	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	7.5	A
Forward voltage (diode)	V_{DSF}	I_{DR} = 2.5 A, V_{GS} = 0 V	—	—	−2.0	V
Reverse recovery time	t_{rr}	I_{DR} = 2.5 A, V_{GS} = 0 V dI_{DR} / dt = 100 A / μs	—	960	—	ns
Reverse recovery charge	Q_{rr}		—	5.3	—	μC

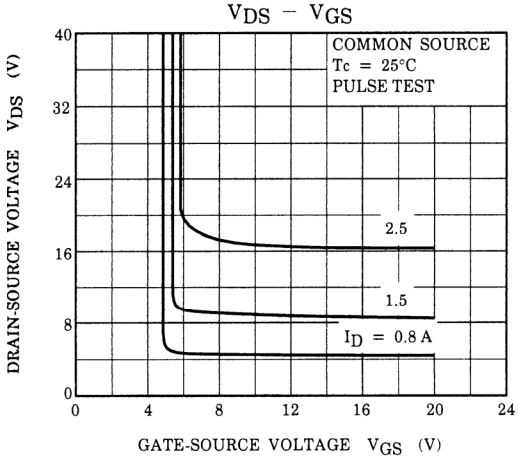
Marking

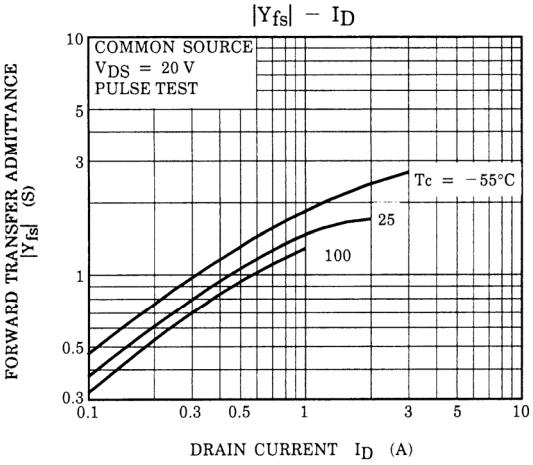


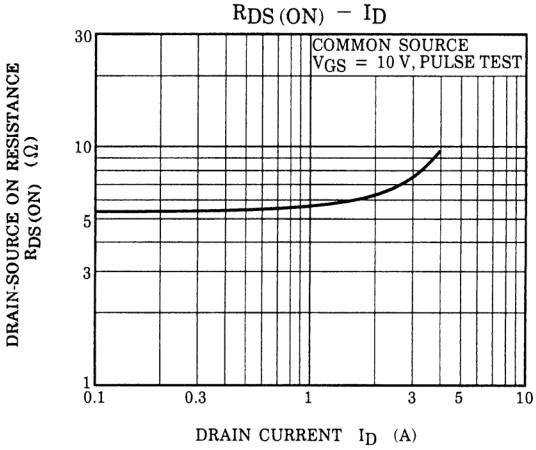

ID − VDS
COMMON SOURCE
Tc = 25°C
PULSE TEST
10
8
6
5.5
5
4.8
4.5
VGS = 4 V
DRAIN CURRENT ID (A)
DRAIN-SOURCE VOLTAGE VDS (V)

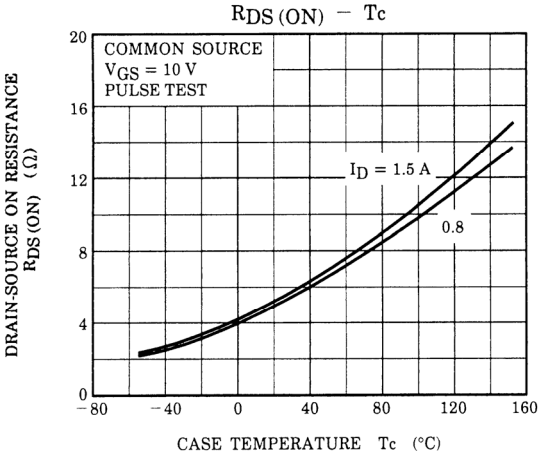

ID − VDS
COMMON SOURCE
Tc = 25°C
PULSE TEST
10
9
8
7
6.5
6
5.5
5
4.5
VGS = 4 V
DRAIN CURRENT ID (A)
DRAIN-SOURCE VOLTAGE VDS (V)

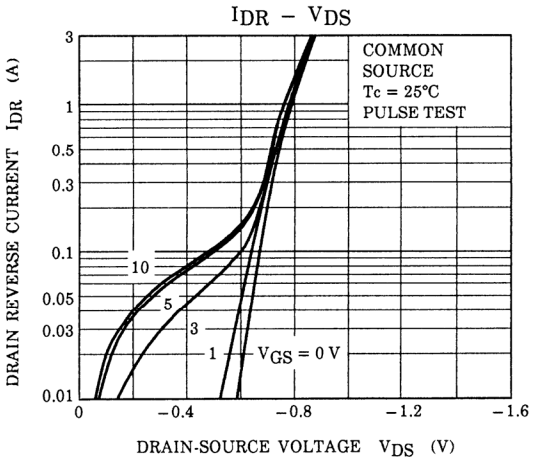

ID − VGS
COMMON SOURCE
VDS = 20V
PULSE TEST
Tc = −55°C
25
100
DRAIN CURRENT ID (A)
GATE-SOURCE VOLTAGE VGS (V)

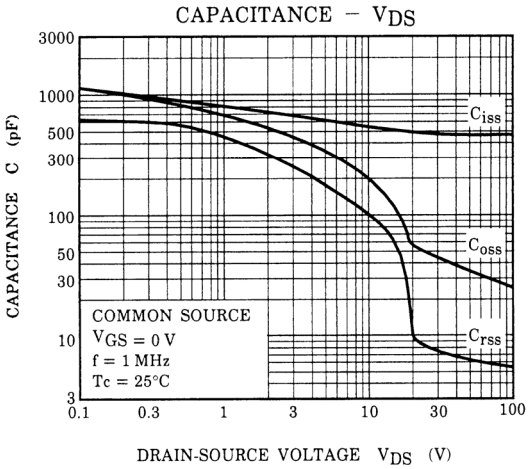

VDS − VGS
COMMON SOURCE
Tc = 25°C
PULSE TEST
2.5
1.5
ID = 0.8 A
DRAIN-SOURCE VOLTAGE VDS (V)
GATE-SOURCE VOLTAGE VGS (V)

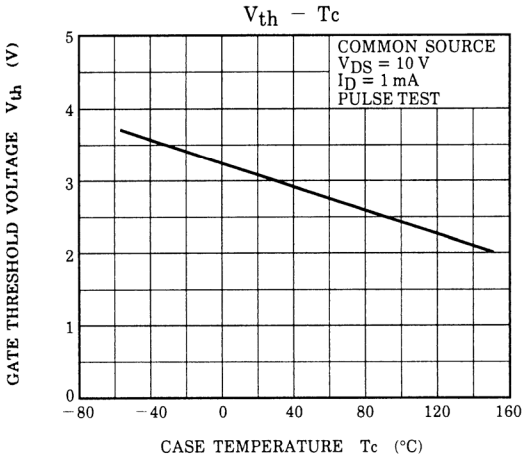

|Yfs| − ID
COMMON SOURCE
VDS = 20 V
PULSE TEST
Tc = −55°C
25
100
FORWARD TRANSFER ADMITTANCE |Yfs| (S)
DRAIN CURRENT ID (A)

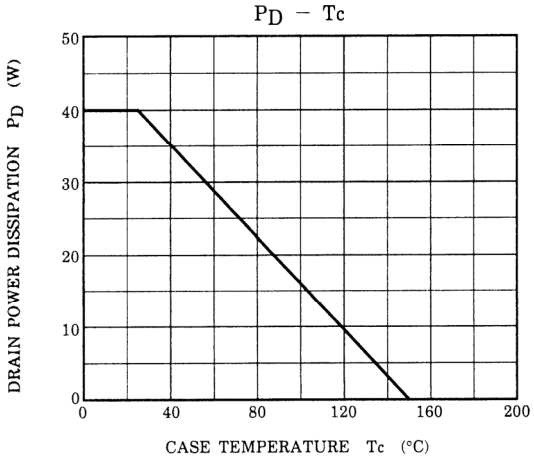

RDS (ON) − ID
COMMON SOURCE
VGS = 10 V, PULSE TEST
DRAIN-SOURCE ON RESISTANCE RDS (ON) (Ω)
DRAIN CURRENT ID (A)

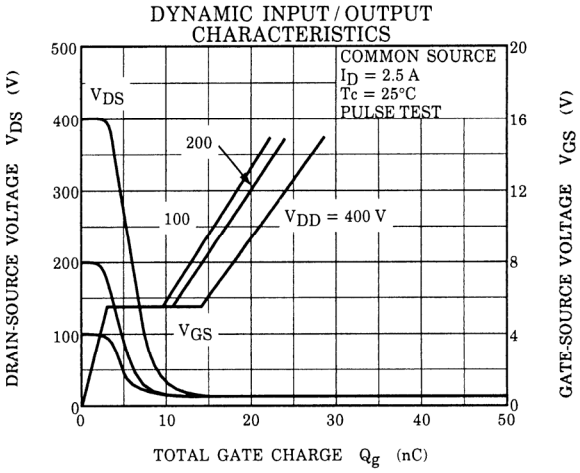

RDS (ON) – Tc
COMMON SOURCE
VGS = 10 V
PULSE TEST
ID = 1.5 A
0.8
DRAIN-SOURCE ON RESISTANCE RDS (ON) (Ω)
CASE TEMPERATURE Tc (°C)

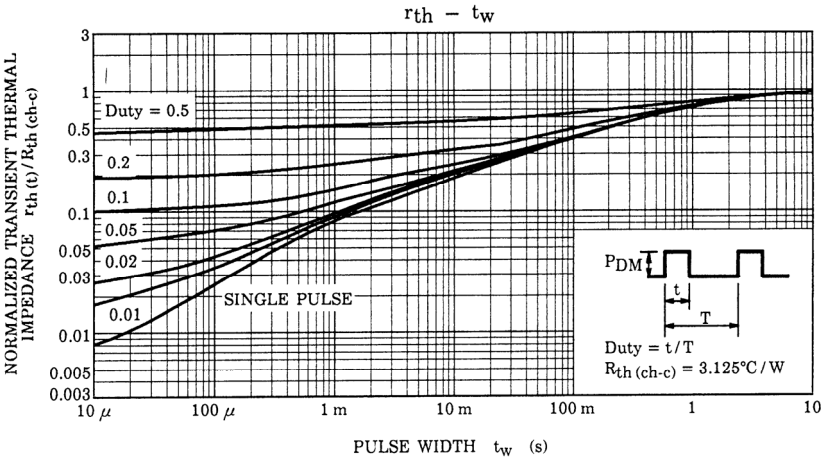

IDR – VDS
COMMON SOURCE
Tc = 25°C
PULSE TEST
10
5
3
1
VGS = 0 V
DRAIN REVERSE CURRENT IDR (A)
DRAIN-SOURCE VOLTAGE VDS (V)

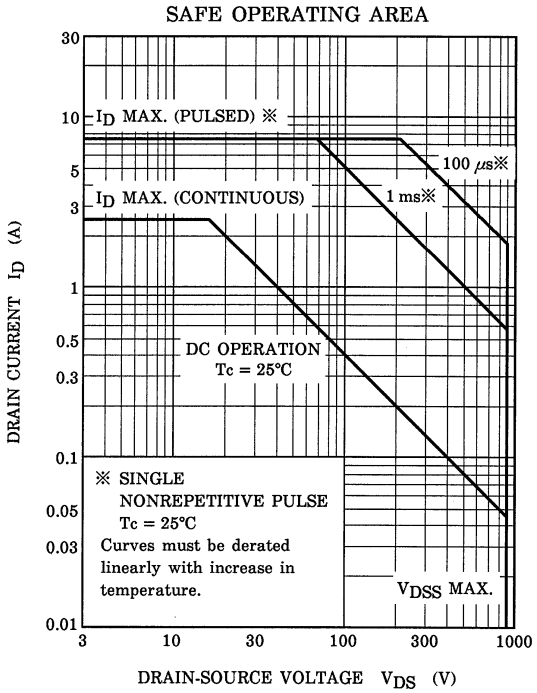

CAPACITANCE – VDS
Ciss
Coss
Crss
COMMON SOURCE
VGS = 0 V
f = 1 MHz
Tc = 25°C
CAPACITANCE C (pF)
DRAIN-SOURCE VOLTAGE VDS (V)

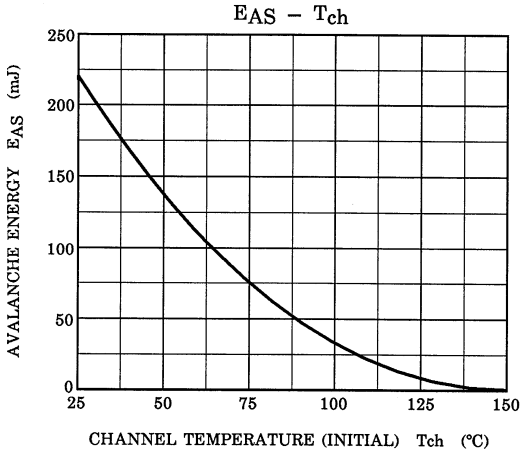

Vth – Tc
COMMON SOURCE
VDS = 10 V
ID = 1 mA
PULSE TEST
GATE THRESHOLD VOLTAGE Vth (V)
CASE TEMPERATURE Tc (°C)

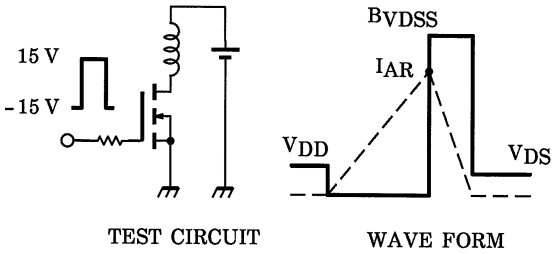

PD – Tc
DRAIN POWER DISSIPATION PD (W)
CASE TEMPERATURE Tc (°C)


DYNAMIC INPUT / OUTPUT CHARACTERISTICS
COMMON SOURCE
ID = 2.5 A
Tc = 25°C
PULSE TEST
VDS
200
100
VDD = 400 V
VGS
DRAIN-SOURCE VOLTAGE VDS (V)
GATE-SOURCE VOLTAGE VGS (V)
TOTAL GATE CHARGE Qg (nC)









$R_G = 25\ \Omega$
$V_{DD} = 90$ V, $L = 63.4$ mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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